

Amendments to the Specification:

In the Specification:

Please amend Paragraph [00015] of the Specification as Filed to read:

[0015] The substrate used may be a metal such as brass that is not attacked by the chemicals used in electroforming processes, or glass with a chrome coating. As illustrated in **FIG. 2B**, a smooth controlled-release layer **18** is applied to the polished surface of the substrate **16**. The smooth controlled-release layer **18** may be achieved by spin coating to apply an organic chemical layer, such as a positive photoresist, approximately 0.5 micron thick onto the substrate base. In one embodiment, the smooth controlled-release layer **18** is chosen to be sacrificial in such that it is inherently brittle and readily dissolved in a solvent such as acetone. Commercially available resists, such as Shipley 1818, dry with a glass-like, striation-free surface

Please amend Paragraph [00018] of the Specification as Filed to read:

[0018] When both layers are plated, the photoresist layer **18** is removed to separate the orifice plate from the mandrel base. For removal and recycling, the orifice plate **14** of **FIG. 1** can be soaked in acetone until the parting or sacrificial resist layer **18** is dissolved, resulting in the structure shown in **FIG. 2H**. Alternatively, the multilayer orifice plate **14** may be carefully peeled, fracturing the brittle parting or sacrificial resist layer **18**. Resist can then be chemically stripped from the orifice plate **14** and the base substrate **16**. The thin copper layer **20** which has remained on the separated orifice plate is then removed with a selective etchant, leaving the completed orifice plate structure shown in **FIG. 2I**. The selective etchant would remove copper but not damage the nickel during the short immersion period required to etch away the copper. The orifice plate is then ready to be assembled into an ink jet printhead.

Applicant believes no new matter has been added with these amendments.